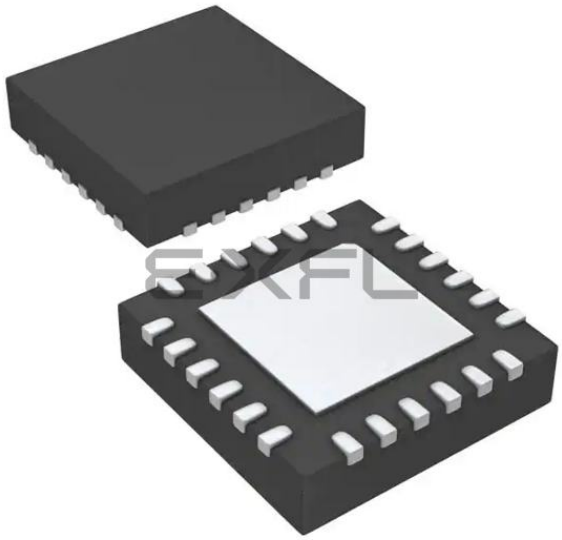

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SMBus (2-Wire/I²C), SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	16
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	0.9V ~ 3.6V
Data Converters	A/D 15x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	24-VFQFN Exposed Pad
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f931-g-gm

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Table 3.3. PCB Land Pattern

Dimension	MIN	MAX
C1	4.80	4.90
C2	4.80	4.90
E	0.50 BSC	
X1	0.20	0.30
X2	3.20	3.40
Y1	0.75	0.85
Y2	3.20	3.40

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
4. A 3 x 3 array of 1.0 mm square openings on 1.2 mm pitch should be used for the center ground pad.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

Table 4.2. Global Electrical Characteristics (Continued)

–40 to +85 °C, 25 MHz system clock unless otherwise specified. See "AN358: Optimizing Low Power Operation of the ‘F9xx" for details on how to achieve the supply current specifications listed in this table.

Parameter	Conditions	Min	Typ	Max	Units
Digital Supply Current—Suspend and Sleep Mode					
Digital Supply Current[6] (Suspend Mode)	V_{DD} = 1.8–3.6 V, two-cell mode	—	77	—	µA
Digital Supply Current (Sleep Mode, SmaRTClock running)	1.8 V, T = 25 °C 3.0 V, T = 25 °C 3.6 V, T = 25 °C 1.8 V, T = 85 °C 3.0 V, T = 85 °C 3.6 V, T = 85 °C (includes SmaRTClock oscillator and VBAT Supply Monitor)	— — — — — —	0.60 0.75 0.85 1.30 1.60 1.90	— — — — — —	µA µA µA µA µA µA
Digital Supply Current (Sleep Mode)	1.8 V, T = 25 °C 3.0 V, T = 25 °C 3.6 V, T = 25 °C 1.8 V, T = 85 °C 3.0 V, T = 85 °C 3.6 V, T = 85 °C (includes VBAT supply monitor)	— — — — — —	0.05 0.08 0.12 0.75 0.90 1.20	— — — — — —	µA µA µA µA µA µA

Notes:

1. Based on device characterization data; Not production tested.
2. SYSCLK must be at least 32 kHz to enable debugging.
3. Digital Supply Current depends upon the particular code being executed. The values in this table are obtained with the CPU executing an “sjmp $” loop, which is the compiled form of a while(1) loop in C. One iteration requires 3 CPU clock cycles, and the Flash memory is read on each cycle. The supply current will vary slightly based on the physical location of the sjmp instruction and the number of Flash address lines that toggle as a result. In the worst case, current can increase by up to 30% if the sjmp loop straddles a 128-byte Flash address boundary (e.g., 0x007F to 0x0080). Real-world code with larger loops and longer linear sequences will have few transitions across the 128-byte address boundaries.
4. Includes oscillator and regulator supply current.
5. IDD can be estimated for frequencies ≤10 MHz by simply multiplying the frequency of interest by the frequency sensitivity number for that range, then adding an offset of 90 µA. When using these numbers to estimate I_{DD} for >10 MHz, the estimate should be the current at 25 MHz minus the difference in current indicated by the frequency sensitivity number. For example: V_{DD} = 3.0 V; F = 20 MHz, I_{DD} = 4.1 mA – (25 MHz – 20 MHz) x 0.120 mA/MHz = 3.5 mA.
6. The supply current specifications in Table 4.2 are for two cell mode. The VBAT current in one-cell mode can be estimated using the following equation:

$$\text{VBAT Current (one-cell mode)} = \frac{\text{Supply Voltage} \times \text{Supply Current (two-cell mode)}}{\text{DC-DC Converter Efficiency} \times \text{VBAT Voltage}}$$

   The VBAT Voltage is the voltage at the VBAT pin, typically 0.9 to 1.8 V.
   The Supply Current (two-cell mode) is the data sheet specification for supply current.
   The Supply Voltage is the voltage at the VDD/DC+ pin, typically 1.8 to 3.3 V (default = 1.9 V).
   The DC-DC Converter Efficiency can be estimated using Figure 4.3–Figure 4.5.
7. Idle IDD can be estimated by taking the current at 25 MHz minus the difference in current indicated by the frequency sensitivity number. For example: V_{DD} = 3.0 V; F = 5 MHz, Idle I_{DD} = 2.5 mA – (25 MHz – 5 MHz) x 0.095 mA/MHz = 0.6 mA.

5.4.1. Window Detector In Single-Ended Mode

Figure 5.5 shows two example window comparisons for right-justified data, with ADC0LTH:ADC0LTL = 0x0080 (128d) and ADC0GTH:ADC0GTL = 0x0040 (64d). The input voltage can range from 0 to VREF x (1023/1024) with respect to GND, and is represented by a 10-bit unsigned integer value. In the left example, an AD0WINT interrupt will be generated if the ADC0 conversion word (ADC0H:ADC0L) is within the range defined by ADC0GTH:ADC0GTL and ADC0LTH:ADC0LTL (if 0x0040 < ADC0H:ADC0L < 0x0080). In the right example, and AD0WINT interrupt will be generated if the ADC0 conversion word is outside of the range defined by the ADC0GT and ADC0LT registers (if ADC0H:ADC0L < 0x0040 or ADC0H:ADC0L > 0x0080). Figure 5.6 shows an example using left-justified data with the same comparison values.

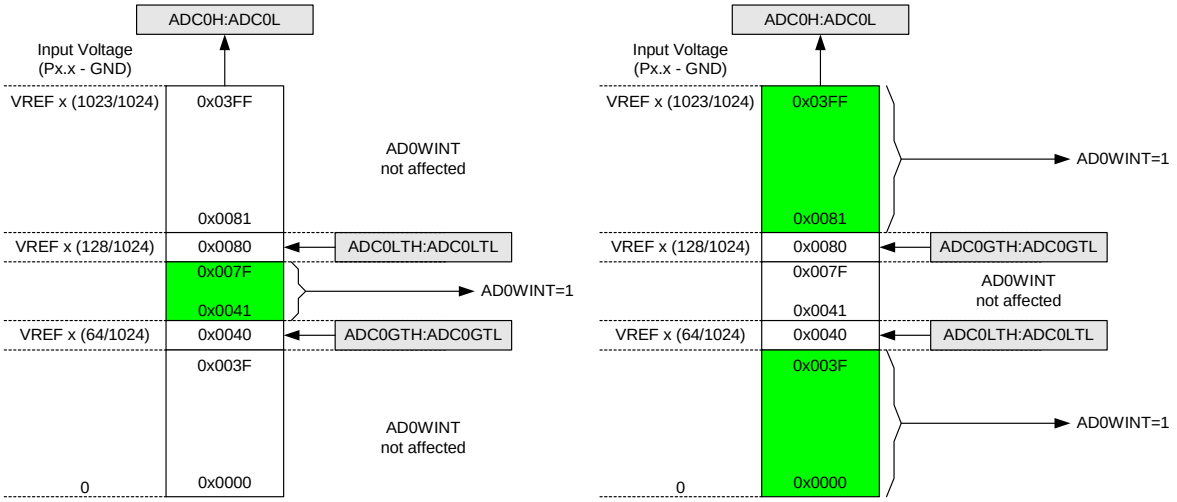

Figure 5.5. ADC Window Compare Example: Right-Justified Single-Ended Data

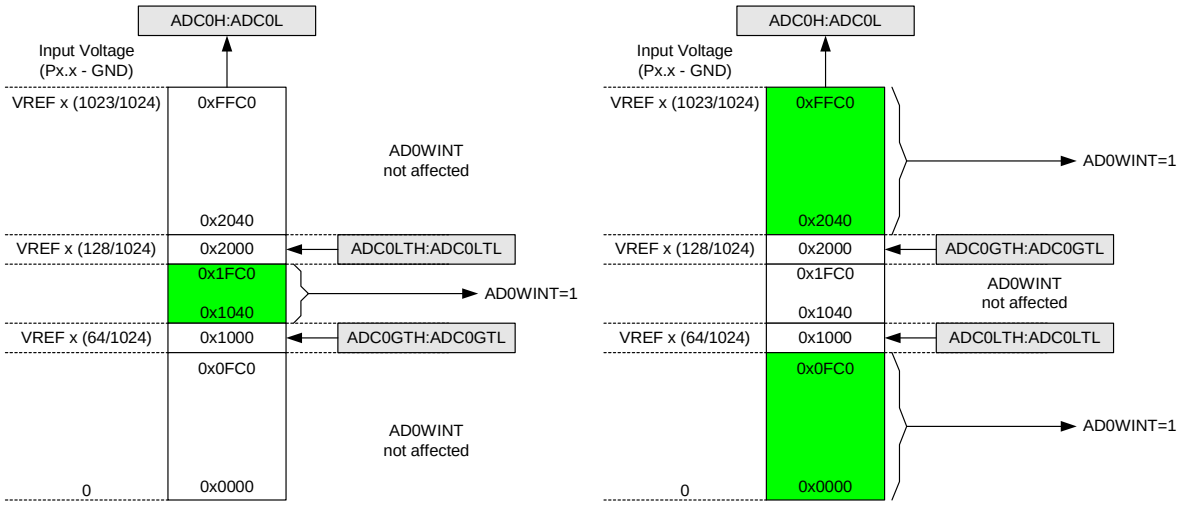

Figure 5.6. ADC Window Compare Example: Left-Justified Single-Ended Data

5.4.2. ADC0 Specifications

See “4. Electrical Characteristics” on page 45 for a detailed listing of ADC0 specifications.

SFR Definition 5.12. ADC0MX: ADC0 Input Channel Select

Bit	7	6	5	4	3	2	1	0
Name				AD0MX				
Type	R	R	R	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	1	1	1	1	1

SFR Page = 0x0; SFR Address = 0xBB

Bit	Name	Function
7:5	Unused	**Unused.** Read = 000b; Write = Don't Care.
4:0	AD0MX	**AMUX0 Positive Input Selection.** Selects the positive input channel for ADC0.

00000:	P0.0	10000:	P2.0 (C8051F920/30 Only)
00001:	P0.1	10001:	P2.1 (C8051F920/30 Only)
00010:	P0.2	10010:	P2.2 (C8051F920/30 Only)
00011:	P0.3	10011:	P2.3 (C8051F920/30 Only)
00100:	P0.4	10100:	P2.4 (C8051F920/30 Only)
00101:	P0.5	10101:	P2.5 (C8051F920/30 Only)
00110:	P0.6	10110:	P2.6 (C8051F920/30 Only)
00111:	P0.7	10111:	Reserved.
01000:	P1.0	11000:	Reserved.
01001:	P1.1	11001:	Reserved.
01010:	P1.2	11010:	Reserved.
01011:	P1.3	11011:	Temperature Sensor*
01100:	P1.4	11100:	VBAT Supply Voltage (0.9–1.8 V) or (1.8–3.6 V)
01101:	P1.5		
01110:	P1.6	11101:	Digital Supply Voltage (VREG0 Output, 1.7 V Typical)
01111:	P1.7 (C8051F920/30 Only)	11110:	VDD/DC+ Supply Voltage (1.8–3.6 V)
		11111:	Ground

***Note:** Before switching the ADC multiplexer from another channel to the temperature sensor, the ADC mux should select the 'Ground' channel as an intermediate step. The intermediate 'Ground' channel selection step will discharge any voltage on the ADC sampling capacitor from the previous channel selection. This will prevent the possibility of a high voltage (> 2V) being presented to the temperature sensor circuit, which can otherwise impact its long-term reliability.

10.4. Multiplexed External Memory Interface

For a Multiplexed external memory interface, the Data Bus and the lower 8-bits of the Address Bus share the same Port pins: AD[7:0]. For most devices with an 8-bit interface, the upper address bits are not used and can be used as GPIO if the external memory interface is used in 8-bit non-banked mode. If the external memory interface is used in 8-bit banked mode, or 16-bit mode, then the address pins will be driven with the upper 4 address bits and cannot be used as GPIO.

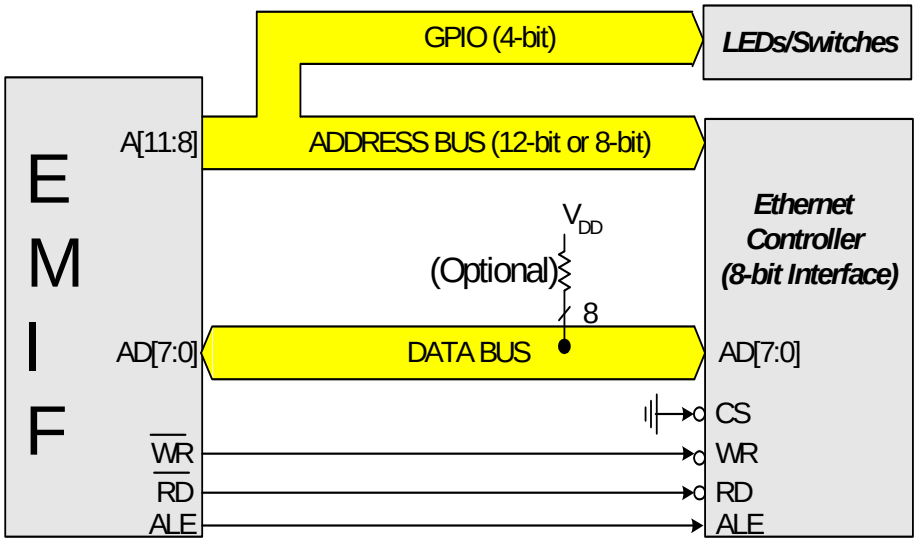

Figure 10.1. Multiplexed Configuration Example

Many devices with a slave parallel memory interface, such as SRAM chips, only support a non-multiplexed memory bus. When interfacing to such a device, an external latch (74HC373 or equivalent logic gate) can be used to hold the lower 8-bits of the RAM address during the second half of the memory cycle when the address/data bus contains data. The external latch, controlled by the ALE (Address Latch Enable) signal, is automatically driven by the External Memory Interface logic. An example SRAM interface showing multiplexed to non-multiplexed conversion is shown in Figure 10.2.

This example is showing that the external MOVX operation can be broken into two phases delineated by the state of the ALE signal. During the first phase, ALE is high and the lower 8-bits of the Address Bus are presented to AD[7:0]. During this phase, the address latch is configured such that the Q outputs reflect the states of the D inputs. When ALE falls, signaling the beginning of the second phase, the address latch outputs remain fixed and are no longer dependent on the latch inputs. Later in the second phase, the Data Bus controls the state of the AD[7:0] port at the time $\overline{RD}$ or $\overline{WR}$ is asserted.

See Section “10.6. External Memory Interface Timing” on page 121 for detailed timing diagrams.

11.1. SFR Paging

To accommodate more than 128 SFRs in the 0x80 to 0xFF address space, SFR paging has been implemented. By default, all SFR accesses target SFR Page 0x0 to allow access to the registers listed in Table 11.1. During device initialization, some SFRs located on SFR Page 0xF may need to be accessed. Table 11.2 lists the SFRs accessible from SFR Page 0x0F. Some SFRs are accessible from both pages, including the SFRPAGE register. SFRs accessible only from Page 0xF are in **bold**.

The following procedure should be used when accessing SFRs from Page 0xF:

Step 1. Save the current interrupt state (EA_save = EA).
Step 2. Disable Interrupts (EA = 0).
Step 3. Set SFRPAGE = 0xF.
Step 4. Access the SFRs located on SFR Page 0xF.
Step 5. Set SFRPAGE = 0x0.
Step 6. Restore interrupt state (EA = EA_save).

Table 11.2. Special Function Register (SFR) Memory Map (Page 0xF)

F8								
F0	B						EIP1	EIP2
E8								
E0	ACC						EIE1	EIE2
D8								
D0	PSW							
C8								
C0								
B8			**ADC0PWR**			**ADC0TK**		
B0								
A8	IE	CLKSEL						
A0	P2				**P0DRV**	**P1DRV**	**P2DRV**	SFRPAGE
98								
90	P1	**CRC0DAT**	**CRC0CN**	**CRC0IN**		**CRC0FLIP**	**CRC0AUTO**	**CRC0CNT**
88								
80	P0	SP	DPL	DPH		**TOFFL**	**TOFFH**	PCON
	0(8)	1(9)	2(A)	3(B)	4(C)	5(D)	6(E)	7(F)

(bit addressable)

SFR Definition 12.6. EIP2: Extended Interrupt Priority 2

Bit	7	6	5	4	3	2	1	0
Name					PSPI1	PRTC0F	PMAT	PWARN
Type	R	R	R	R	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Page = All Pages; SFR Address = 0xF7

Bit	Name	Function
7:4	Unused	**Unused.** Read = 0000b. Write = Don't care.
3	PSPI1	**Serial Peripheral Interface (SPI1) Interrupt Priority Control.** This bit sets the priority of the SPI1 interrupt. 0: SP1 interrupt set to low priority level. 1: SPI1 interrupt set to high priority level.
2	PRTC0F	**SmaRTClock Oscillator Fail Interrupt Priority Control.** This bit sets the priority of the SmaRTClock Alarm interrupt. 0: SmaRTClock Alarm interrupt set to low priority level. 1: SmaRTClock Alarm interrupt set to high priority level.
1	PMAT	**Port Match Interrupt Priority Control.** This bit sets the priority of the Port Match Event interrupt. 0: Port Match interrupt set to low priority level. 1: Port Match interrupt set to high priority level.
0	PWARN	**VDD/DC+ Supply Monitor Early Warning Interrupt Priority Control.** This bit sets the priority of the VDD/DC+ Supply Monitor Early Warning interrupt. 0: VDD/DC+ Supply Monitor Early Warning interrupt set to low priority level. 1: VDD/DC+ Supply Monitor Early Warning interrupt set to high priority level.

13.5. Flash Write and Erase Guidelines

Any system which contains routines which write or erase Flash memory from software involves some risk that the write or erase routines will execute unintentionally if the CPU is operating outside its specified operating range of VDD, system clock frequency, or temperature. This accidental execution of Flash modifying code can result in alteration of Flash memory contents causing a system failure that is only recoverable by re-Flashing the code in the device.

To help prevent the accidental modification of Flash by firmware, the VDD Monitor must be enabled and enabled as a reset source on C8051F92x-C8051F93x devices for the Flash to be successfully modified. **If either the VDD Monitor or the VDD Monitor reset source is not enabled, a Flash Error Device Reset will be generated when the firmware attempts to modify the Flash.**

The following guidelines are recommended for any system that contains routines which write or erase Flash from code.

13.5.1. VDD Maintenance and the VDD Monitor

1. If the system power supply is subject to voltage or current "spikes," add sufficient transient protection devices to the power supply to ensure that the supply voltages listed in the Absolute Maximum Ratings table are not exceeded.
2. Make certain that the maximum VBAT ramp time specification of 3 ms is met. This specification is outlined in Table 4.4 on page 59. On silicon revision F and later revisions, if the system cannot meet this rise time specification, then add an external VDD brownout circuit to the $\overline{\text{RST}}$ pin of the device that holds the device in reset until VDD reaches the minimum device operating voltage and re-asserts $\overline{\text{RST}}$ if VDD drops below the minimum device operating voltage.
3. Keep the on-chip VDD Monitor enabled and enable the VDD Monitor as a reset source as early in code as possible. This should be the first set of instructions executed after the Reset Vector. For C-based systems, this will involve modifying the startup code added by the 'C' compiler. See your compiler documentation for more details. Make certain that there are no delays in software between enabling the VDD Monitor and enabling the VDD Monitor as a reset source. Code examples showing this can be found in “AN201: Writing to Flash from Firmware," available from the Silicon Laboratories web site.

   Notes:
   On C8051F93x-C8051F92x devices, both the VDD Monitor and the VDD Monitor reset source must be enabled to write or erase Flash without generating a Flash Error Device Reset.

   On C8051F93x-C8051F92x devices, both the VDD Monitor and the VDD Monitor reset source are enabled by hardware after a power-on reset.
4. As an added precaution, explicitly enable the VDD Monitor and enable the VDD Monitor as a reset source inside the functions that write and erase Flash memory. The VDD Monitor enable instructions should be placed just after the instruction to set PSWE to a '1', but before the Flash write or erase operation instruction.
5. Make certain that all writes to the RSTSRC (Reset Sources) register use direct assignment operators and explicitly DO NOT use the bit-wise operators (such as AND or OR). For example, "RSTSRC = 0x02" is correct, but "RSTSRC |= 0x02" is incorrect.
6. Make certain that all writes to the RSTSRC register explicitly set the PORSF bit to a '1'. Areas to check are initialization code which enables other reset sources, such as the Missing Clock Detector or Comparator, for example, and instructions which force a Software Reset. A global search on "RSTSRC" can quickly verify this.

14. Power Management

C8051F93x-C8051F92x devices support 5 power modes: Normal, Idle, Stop, Suspend, and Sleep. The power management unit (PMU0) allows the device to enter and wake-up from the available power modes. A brief description of each power mode is provided in Table 14.1. Detailed descriptions of each mode can be found in the following sections.

Table 14.1. Power Modes

Power Mode	Description	Wake-Up Sources	Power Savings
Normal	Device fully functional	N/A	Excellent MIPS/mW
Idle	All peripherals fully functional. Very easy to wake up.	Any Interrupt.	Good No Code Execution
Stop	Legacy 8051 low power mode. A reset is required to wake up.	Any Reset.	Good No Code Execution Precision Oscillator Disabled
Suspend	Similar to Stop Mode, but very fast wake-up time and code resumes execution at the next instruction.	SmaRTClock, Port Match, Comparator0, $\overline{\text{RST}}$ pin.	Very Good No Code Execution All Internal Oscillators Disabled System Clock Gated
Sleep	Ultra Low Power and flexible wake-up sources. Code resumes execution at the next instruction. Comparator0 only functional in two-cell mode.	SmaRTClock, Port Match, Comparator0, $\overline{\text{RST}}$ pin.	Excellent Power Supply Gated All Oscillators except SmaRT-Clock Disabled

In battery powered systems, the system should spend as much time as possible in sleep mode in order to preserve battery life. When a task with a fixed number of clock cycles needs to be performed, the device should switch to normal mode, finish the task as quickly as possible, and return to sleep mode. Idle mode and suspend modes provide a very fast wake-up time; however, the power savings in these modes will not be as much as in sleep Mode. Stop Mode is included for legacy reasons; the system will be more power efficient and easier to wake up when idle, suspend, or sleep mode are used.

Although switching power modes is an integral part of power management, enabling/disabling individual peripherals as needed will help lower power consumption in all power modes. Each analog peripheral can be disabled when not in use or placed in a low power mode. Digital peripherals such as timers or serial busses draw little power whenever they are not in use. Digital peripherals draw no power in Sleep Mode.

16.2. High Power Applications

The dc-dc converter is designed to provide the system with 65 mW of output power, however, it can safely provide up to 100 mW of output power without any risk of damage to the device. For high power applications, the system should be carefully designed to prevent unwanted VBAT and VDD/DC+ Supply Monitor resets, which are more likely to occur when the dc-dc converter output power exceeds 65mW. In addition, output power above 65 mW causes the dc-dc converter to have relaxed output regulation, high output ripple and more analog noise. At high output power, an inductor with low DC resistance should be chosen in order to minimize power loss and maximize efficiency.

The combination of high output power and low input voltage will result in very high peak and average inductor currents. If the power supply has a high internal resistance, the transient voltage on the VBAT terminal could drop below 0.9 V and trigger a VBAT Supply Monitor Reset, even if the open-circuit voltage is well above the 0.9 V threshold. While this problem is most often associated with operation from very small batteries or batteries that are near the end of their useful life, it can also occur when using bench power supplies that have a slow transient response; the supply's display may indicate a voltage above 0.9 V, but the minimum voltage on the VBAT pin may be lower. A similar problem can occur at the output of the dc-dc converter: using the default low current limit setting (125 mA) can trigger V_{DD} Supply Monitor resets if there is a high transient load current, particularly if the programmed output voltage is at or near 1.8 V.

16.3. Pulse Skipping Mode

The dc-dc converter allows the user to set the minimum pulse width such that if the duty cycle needs to decrease below a certain width in order to maintain regulation, an entire "clock pulse" will be skipped.

Pulse skipping can provide substantial power savings, particularly at low values of load current. The converter will continue to maintain a minimum output voltage at its programmed value when pulse skipping is employed, though the output voltage ripple can be higher. Another consideration is that the dc-dc will operate with pulse-frequency modulation rather than pulse-width modulation, which makes the switching frequency spectrum less predictable; this could be an issue if the dc-dc converter is used to power a radio. Figure 4.5 and Figure 4.6 on page 52 and 53 show the effect of pulse skipping on power consumption.

18.2. Power-Fail (VDD/DC+ Supply Monitor) Reset

C8051F93x-C8051F92x devices have a VDD/DC+ Supply Monitor that is enabled and selected as a reset source after each power-on or power-fail reset. When enabled and selected as a reset source, any power down transition or power irregularity that causes VDD/DC+ to drop below V_{RST} will cause the $\overline{RST}$ pin to be driven low and the CIP-51 will be held in a reset state (see Figure 18.3). When VDD/DC+ returns to a level above V_{RST}, the CIP-51 will be released from the reset state.

After a power-fail reset, the PORSF flag reads 1, the contents of RAM invalid, and the VDD/DC+ supply monitor is enabled and selected as a reset source. The enable state of the VDD/DC+ supply monitor and its selection as a reset source is only altered by power-on and power-fail resets. For example, if the VDD/DC+ supply monitor is de-selected as a reset source and disabled by software, then a software reset is performed, the VDD/DC+ supply monitor will remain disabled and de-selected after the reset.

In battery-operated systems, the contents of RAM can be preserved near the end of the battery's usable life if the device is placed in sleep mode prior to a power-fail reset occurring. When the device is in sleep mode, the power-fail reset is automatically disabled and the contents of RAM are preserved as long as the VBAT supply does not fall below V_{POR}. A large capacitor can be used to hold the power supply voltage above V_{POR} while the user is replacing the battery. Upon waking from sleep mode, the enable and reset source select state of the VDD/DC+ supply monitor are restored to the value last set by the user.

To allow software early notification that a power failure is about to occur, the VDDOK bit is cleared when the VDD/DC+ supply falls below the V_{WARN} threshold. The VDDOK bit can be configured to generate an interrupt. See Section "12. Interrupt Handler" on page 136 for more details.

Important Note: To protect the integrity of Flash contents, **the VDD/DC+ supply monitor must be enabled and selected as a reset source if software contains routines which erase or write Flash memory.** If the VDD/DC+ supply monitor is not enabled, any erase or write performed on Flash memory will cause a Flash Error device reset.

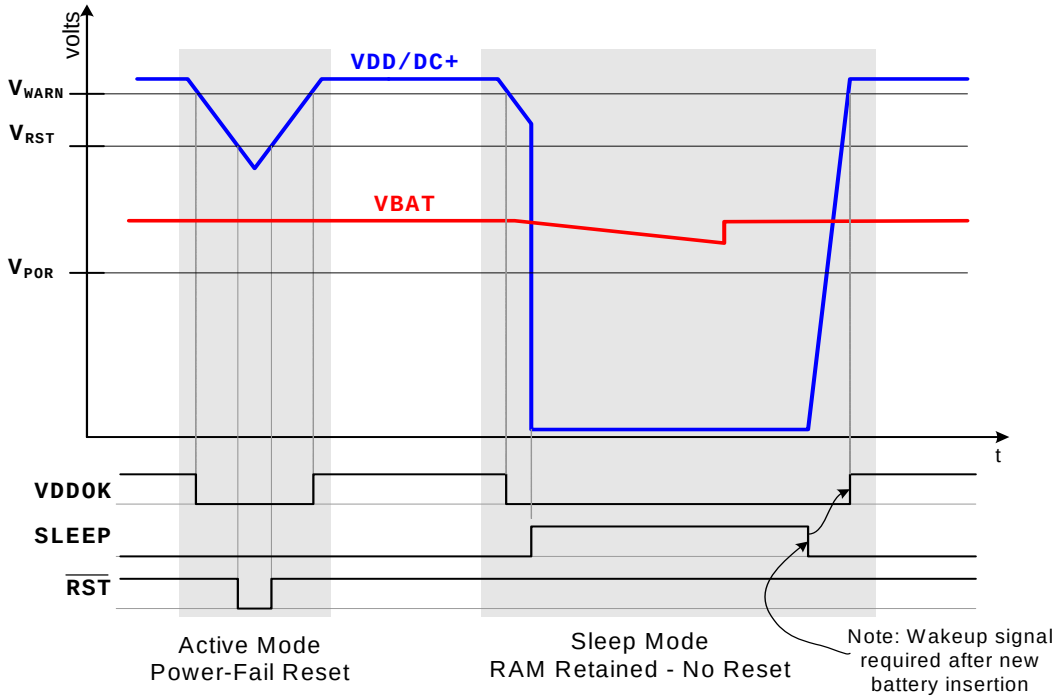

Figure 18.3. Power-Fail Reset Timing Diagram

SFR Definition 21.8. P0: Port0

Bit	7	6	5	4	3	2	1	0
Name	P0[7:0]							
Type	R/W							
Reset	1	1	1	1	1	1	1	1

SFR Page = All Pages; SFR Address = 0x80; Bit-Addressable

Bit	Name	Description	Write	Read
7:0	P0[7:0]	**Port 0 Data.** Sets the Port latch logic value or reads the Port pin logic state in Port cells configured for digital I/O.	0: Set output latch to logic LOW. 1: Set output latch to logic HIGH.	0: P0.n Port pin is logic LOW. 1: P0.n Port pin is logic HIGH.

SFR Definition 21.9. P0SKIP: Port0 Skip

Bit	7	6	5	4	3	2	1	0
Name	P0SKIP[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page= 0x0; SFR Address = 0xD4

Bit	Name	Function
7:0	P0SKIP[7:0]	**Port 0 Crossbar Skip Enable Bits.** These bits select Port 0 pins to be skipped by the Crossbar Decoder. Port pins used for analog, special functions or GPIO should be skipped by the Crossbar. 0: Corresponding P0.n pin is not skipped by the Crossbar. 1: Corresponding P0.n pin is skipped by the Crossbar.

SFR Definition 21.12. P0DRV: Port0 Drive Strength

Bit	7	6	5	4	3	2	1	0
Name	P0DRV[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0xF; SFR Address = 0xA4

Bit	Name	Function
7:0	P0DRV[7:0]	**Drive Strength Configuration Bits for P0.7–P0.0 (respectively).** Configures digital I/O Port cells to high or low output drive strength. 0: Corresponding P0.n Output has low output drive strength. 1: Corresponding P0.n Output has high output drive strength.

23.2. Operational Modes

UART0 provides standard asynchronous, full duplex communication. The UART mode (8-bit or 9-bit) is selected by the S0MODE bit (SCON0.7). Typical UART connection options are shown below.

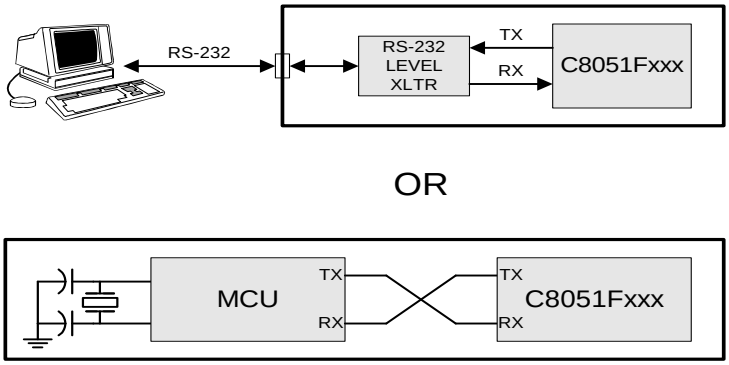

Figure 23.3. UART Interconnect Diagram

23.2.1. 8-Bit UART

8-Bit UART mode uses a total of 10 bits per data byte: one start bit, eight data bits (LSB first), and one stop bit. Data are transmitted LSB first from the TX0 pin and received at the RX0 pin. On receive, the eight data bits are stored in SBUF0 and the stop bit goes into RB80 (SCON0.2).

Data transmission begins when software writes a data byte to the SBUF0 register. The TI0 Transmit Interrupt Flag (SCON0.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN0 Receive Enable bit (SCON0.4) is set to logic 1. After the stop bit is received, the data byte will be loaded into the SBUF0 receive register if the following conditions are met: RI0 must be logic 0, and if MCE0 is logic 1, the stop bit must be logic 1. In the event of a receive data overrun, the first received 8 bits are latched into the SBUF0 receive register and the following overrun data bits are lost.

If these conditions are met, the eight bits of data is stored in SBUF0, the stop bit is stored in RB80 and the RI0 flag is set. If these conditions are not met, SBUF0 and RB80 will not be loaded and the RI0 flag will not be set. An interrupt will occur if enabled when either TI0 or RI0 is set.

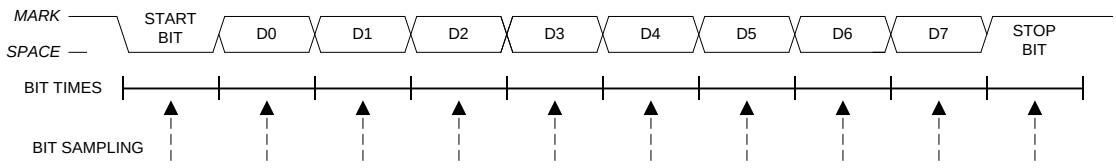

Figure 23.4. 8-Bit UART Timing Diagram

SFR Definition 25.11. TMR2L: Timer 2 Low Byte

Bit	7	6	5	4	3	2	1	0
Name	TMR2L[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xCC

Bit	Name	Function
7:0	TMR2L[7:0]	**Timer 2 Low Byte.** In 16-bit mode, the TMR2L register contains the low byte of the 16-bit Timer 2. In 8-bit mode, TMR2L contains the 8-bit low byte timer value.

SFR Definition 25.12. TMR2H Timer 2 High Byte

Bit	7	6	5	4	3	2	1	0
Name	TMR2H[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xCD

Bit	Name	Function
7:0	TMR2H[7:0]	**Timer 2 High Byte.** In 16-bit mode, the TMR2H register contains the high byte of the 16-bit Timer 2. In 8-bit mode, TMR2H contains the 8-bit high byte timer value.